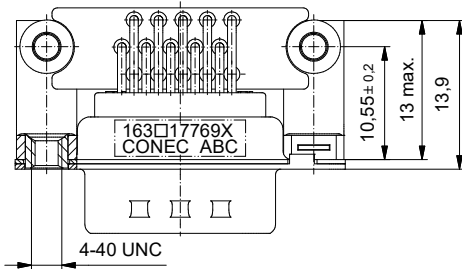
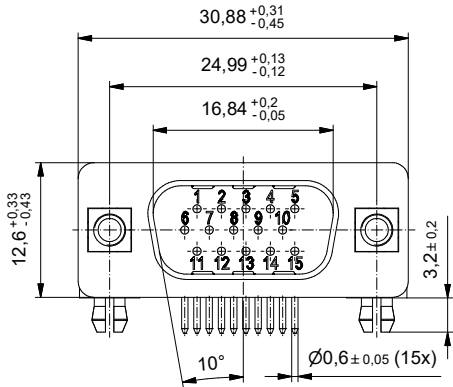
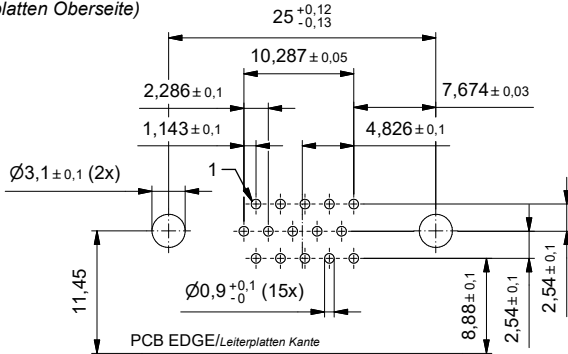


PCB hole drillings
(PCB top side)
Leiterplattenbohrbild
(Leiterplatten Oberseite)



**Technical specification/
Technische Daten:**

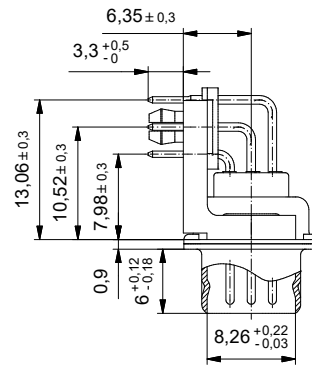
Working voltage/ Betriebsspannung:	60 V AC
Insulation resistance/ Isolationswiderstand:	≥ 5 GΩ
Dielectric withstanding voltage/ Spannungsfestigkeit:	1000 V, 50 Hz, 1 min.
Temperature range/ Temperaturbereich:	- 55 °C ... + 125 °C
Current rating/ Strombelastbarkeit:	3,0 A (UL, VDE) / 2,5 A (CSA)
Mating cycles/ Steckzyklen:	Quality class 1 = 500 Gütestufe 1 Quality class 2 = 200 Gütestufe 2 Quality class 3 = 50 Gütestufe 3 Quality class 4 ≥ 500 Gütestufe 4

**Materials/
Werkstoffe:**

Contact/ Kontakt:	Cu alloy, Au over Ni
Insulator/ Isolierkörper:	PBT GF UL 94 V-0
Fixing plate/ Zentrierplatte:	PBT GF UL 94 V-0
Shell/ Gehäuse:	Steel, Sn over Ni
Metal bracket/ Metallwinkel:	GD-Zn, Sn over Ni
Threaded insert/ Gewindeinsatz:	Cu alloy, Sn over Ni
PCB snap/ PCB Clip:	Cu alloy, Sn over Ni

**Installation specification/
Montagedaten:**

Recommended torque value for thread/ Empfohlenes Drehmoment für Gewinde:	max. 6 in.LB/ max. 67 Ncm
PCB snap for hole diameter/ PCB Clip für Lochdurchmesser:	Ø3,1 mm
Circuit board thickness/ Leiterplattenstärke:	1,6 mm



Part no. / Part marked/ Art.-Nr. / Bedruckung:	Quality class/ Gütestufe:	Contact plating/ Kontakt Veredelung:
163J17769X	4	50 µm hard gold over min. 50 µm nickel 50 µm Gold über min. 50 µm Nickel
163A17769X	3	Gold flash over nickel Gold über Nickel
163B17769X	2	20 µm hard gold over min. 50 µm nickel 20 µm Gold über min. 50 µm Nickel
163C17769X	1	30 µm hard gold over min. 50 µm nickel 30 µm Gold über min. 50 µm Nickel

Index: a Original	Scale/ Maßstab: 2:1		D-SUB HD Male 90° 15pos. Solder pin angled 0.350 inch threaded insert, metal bracket, fixing plate, PCB snap D-SUB HD Stift 90° 15pos. Lötstift abgewinkelt 7.98 mm Gewindeinsatz, Metallwinkel, Zentrierplatte, PCB Clip	dwg no / Z.-nr.: 16K1A4168	DIN- A3
Status: InBearbeitung					
RoHS compliant/konform					1 / 1

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